

INTERCONNECTS

SERIES 802 & 803 • .100" GRID (.030" DIA. PINS), SOLDERLESS PRESS-FIT • DOUBLE ROW STRIPS

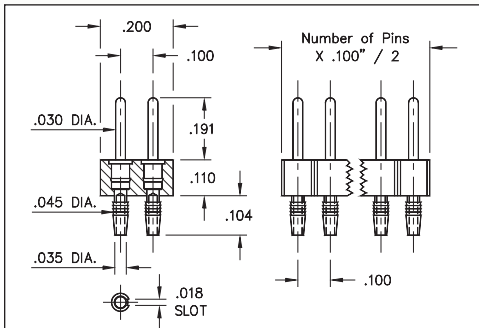


FIG. 1

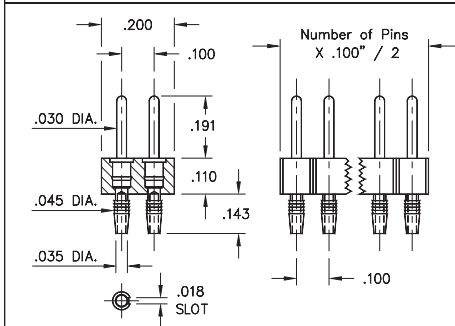


FIG. 2

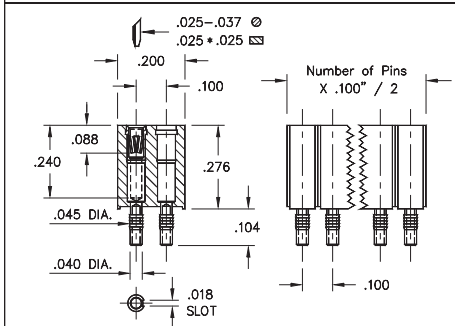


FIG. 3

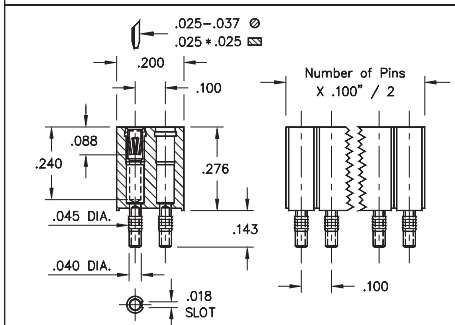
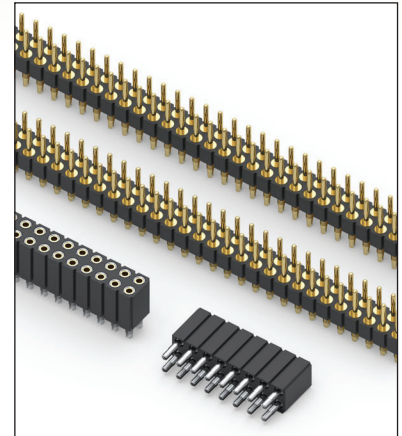


FIG. 4

- The unique compliant tail pins conform to .040"±.003" finished hole without stressing inner layers. Patent No. 4,799,904
- Headers and sockets are available for board thicknesses of .060" - .100" and .090" - .130". See ordering information for details
- Series 802 pin headers use MM #5601 and #5602 compliant tail pins featuring a .030" dia. mating lead. See page 220 for details
- Series 803 sockets with MM #4614 or #4615 pins use Hi-Rel, 6-finger BeCu #47 contact rated at 4.5 amps. Receptacles accept .030" diameter pins & .025" square pins. See pg. 256 for details
- Insulators are high temperature thermoplastic



ORDERING INFORMATION

FIG. 1	Compliant Tail Pin Header for .060" - .100" Thick Boards				
	802-XX-0-61-001000 Specify number of pins 04-64				
FIG. 2	Compliant Tail Pin Header for .090" - .130" Thick Boards				
	802-XX-0-62-001000 Specify number of pins 04-64				
RoHS-2 2011/65/EU XX=Plating Code See Below For Electrical, Mechanical & Environmental Data, See page 264					
SPECIFY PLATING CODE XX=		10 	90	40 	
Pin Plating 		10 μ" Au	200 μ" Sn/Pb	200 μ" Sn	

FIG. 3	Compliant Tail Socket for .060" - .100" Thick Boards							
	803-XX-__-__-61-001000 Specify number of pins 004-100							
FIG. 4	Compliant Tail Socket for .090" - .130" Thick Boards							
	803-XX-__-__-62-001000 Specify number of pins 004-100							
RoHS-2 2011/65/EU XX=Plating Code See Below For Electrical, Mechanical & Environmental Data, See page 264								
SPECIFY PLATING CODE XX=								
Sleeve (Pin)	11	13	91	93	99	41	43	44
	10 μ" Au	10 μ" Au	200 μ" Sn/Pb	200 μ" Sn/Pb	200 μ" Sn/Pb	200 μ" Sn	200 μ" Sn	200 μ" Sn
Contact (Clip)	10 μ" Au	30 μ" Au	10 μ" Au	30 μ" Au	100 μ" Sn/Pb	10 μ" Au	30 μ" Au	100 μ" Sn

